


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13410	
1.3 Title of PCN	ST MUAR (Malaysia) die attach material (Glue) additional source for STM32 LQFP 14x14 SHD 100L package - on listed products	
1.4 Product Category	STM32 in LQFP 14x14 SHD 100L package	
1.5 Issue date	2022-06-24	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Die Attach material	ST MUAR (Malaysia)

4. Description of change

	Old	New
4.1 Description	STM32 LQFP 14x14 SHD 100L package current die attach material is glue Loctite Ablestik ABP8302	STM32 LQFP 14x14 SHD 100L package Die attach material : - glue Loctite Ablestik ABP8302 - current - glue Hitachi EN4900GC - additional
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	We are facing a Shortage of GLUE LOCTITE ABLESTIK ABP8302 due to COVID-19 lockdown in Shanghai. For STM32 LQFP 14x14 SHD 100L listed devices we can replace the glue by GLUE HITACHI EN4900GC since this Glue is already used and qualified for LQFP 10x10 64L with same LF finishing and same wire. To minimize the risk ST Microcontrollers Division decided to use an already qualified in ST product as additional glue to maintain state of the art service level to our customers and avoid line stop.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tool
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7. Timing / schedule

7.1 Date of qualification results	2022-05-19
7.2 Intended start of delivery	2022-05-25
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	13410 MDG-MCD RER1514- LQFP7x7 Muar-PCN9484- reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-06-24

9. Attachments (additional documentations)

13410 Public product.pdf
 13410 MDG-MCD RER1514- LQFP7x7 Muar-PCN9484- reliability evaluation report.pdf
 13410 PCN13410_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F071V8T6	
	STM32F071V8T6TR	
	STM32F071V8T7	
	STM32F071V8T7TR	
	STM32F071VBT6	
	STM32F071VBT6TR	
	STM32F072V8T6	
	STM32F072VBT6	
	STM32F078VBT6	
	STM32F091VBT6	
	STM32F091VBT7	
	STM32F091VCT6	
	STM32F091VCT6TR	
	STM32F091VCT7	
	STM32F091VCT7TR	
	STM32F098VCT6	
	STM32F100V8T6B	
	STM32F100V8T6BTR	
	STM32F100V8T7B	
	STM32F100VBT6B	
	STM32F100VBT6BTR	
	STM32F100VBT7B	
	STM32F100VCT6B	
	STM32F100VDT6B	
	STM32F100VDT7B	
	STM32F100VET7B	
	STM32F101V8T6	
	STM32F101V8T6TR	
	STM32F101VBT6	
	STM32F101VCT6	
	STM32F101VCT6TR	
	STM32F101VDT6	
	STM32F101VET6	
	STM32F101VET6TR	
	STM32F101VFT6	
	STM32F101VGT6	
	STM32F103V8T6	
	STM32F103V8T6TR	
	STM32F103VBT6	

	STM32F103VBT6TR	
	STM32F103VBT7	
	STM32F103VCT6	
	STM32F103VCT6TR	
	STM32F103VDT6	
	STM32F103VDT6TR	
	STM32F103VDT7	
	STM32F103VET6	
	STM32F103VET6TR	
	STM32F103VET7	
	STM32F103VFT6	
	STM32F103VFT6TR	
	STM32F103VFT7	
	STM32F103VGT6	
	STM32F103VGT6TR	
	STM32F103VGT7	
	STM32F105V8T6	
	STM32F105VBT6	
	STM32F105VCT6	
	STM32F105VCT6TR	
	STM32F105VCT7	
	STM32F107VBT6	
	STM32F107VCT6	
	STM32F107VCT6TR	
	STM32F107VCT7	
	STM32F302VBT6	
	STM32F302VBT6TR	
	STM32F302VCT6	
	STM32F302VCT6TR	
	STM32F302VCT7	
	STM32F302VDT6	
	STM32F302VET6	
	STM32F302VET6TR	
	STM32F303VBT6	
	STM32F303VBT6TR	
	STM32F303VCT6	
	STM32F303VCT6TR	
	STM32F303VCT7	
	STM32F303VDT6	
	STM32F303VET6	
	STM32F303VET6TR	
	STM32F303VET7	
	STM32F358VCT6	
	STM32F398VET6	

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MMS- MCD RER1514

Reliability Report

Qualification Type : ASSEMBLY LINE QUALIFICATION, NEW BILL OF MATERIALS

LQFP 7x7 48L - ST Muar Qualification

Dice 410/427/765

(PCN MMS-MIC/15/9484 dated 30 Oct 2015)

Product / Process & Package Information	Die 410	Die 427	Die 765
Commercial Product:	STM32F103CBT6	STM32L152CCT6	STM8S207C8T6
Product Line:	STM32F die 410	STM32L die 427	STM8S die 765
Product Description:	Micro 32Bits		Micro 8Bits
Finish Good Code:	ES32F103CBT6\$J8	ES32L152CCT6\$B6	ES8S207C8T6\$9C
Mask Set Revision:	X410XXXX	X427XXXV	X765XXXV
Silicon Process Technology:	0.18 M8 EMBEDDED FLASH	8X - CMOSF9S	2V - CMOSF9
Wafer Fabrication Location:	TSMC Fab 3 Taiwan	ST Rousset 8 France	ST Rousset 8 France
Electrical Wafer Sort Test Plant Location:	ST MICROELECTRONICS Ang Mo Kio EWS SINGAPORE		ARDENTEC Hsinchu EWS Taiwan
Package:	LQFP 48 7x7x1.4		
Assembly Plant location:	ST Muar (Malaysia)		
Final Test plant location:	ST Muar (Malaysia)		

Approval List			
Function	Location	Name	Date
Division Q&R Responsible	ST Rousset	Gisèle SEUBE	May31st, 2016
Division Quality Manager	ST Rousset	Pascal NARCHE	May31st, 2016

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1 RELIABILITY RESULTS OVERVIEW

1.1 Objectives

This report summarizes the reliability results for LQFP 48 7x7 package manufactured at ST Muar (Malaysia).

Test vehicles are described here below:

Product	Package
STM32F103CBT6	LQFP 48 7x7x1.4
STM32L152CCT6	LQFP 48 7x7x1.4
STM8S207C8T6	LQFP 48 7x7x1.4

1.2 Context

In order to increase assembly capacity, ST Microcontrollers Division has decided to add a High Density line in ST Muar (Malaysia) assembly site, for LQFP 48 7x7 products.

New Bill of Materials changes are described here below for LQFP 7x7 48L products:

	Existing Bill Of Materials			Added Bill Of Materials
Assembly site	STATS ChipPAC Shanghai (China)	Amkor ATP (Philippines)	ST Muar (Malaysia)	ST Muar (Malaysia)
Wire	Gold 0.8mil	Gold 0.8mil	Gold 0.8mil	Silver 0.8mil
Leadframe	Copper Frame Spot Ag	Copper Frame Spot Ag	Pre Plated Frame	Pre Plated Frame
Leadfinishing (*1)	Pure Tin (e3)	Pure Tin (e3)	Rough Ni Pd AgAu (e4)	Rough Ni Pd AgAu (e4)
Resin	Sumitomo G700E	Sumitomo G631HQ	Sumitomo G700LS	Sumitomo G700LS
Glue	Ablestik 3230	Evertch AP4200	Hitachi EN4900	Hitachi EN4900

According to the positive reliability results, the qualification is granted for High Density assembly line in ST Muar (Malaysia).

2 RELIABILITY TEST VEHICLES Characteristics

2.1 Reliability Test vehicles description

Package line	Assembly Line	Package	Device (Partial RawLine Code)	Diffusion Process	Number of Lots
HD LQFP	LQFP7*7	48L	STM8S (5B*765)	F9GO1	1
			STM32F (5B*410)	TSMC 0.18µm	1
			STM32L (5B*427)	F9GO2S	1

2.2 Reliability Information

Lot ID	Lot 1	Lot 2	Lot 3
Die Name /cut:	410	427	765
Diffusion Lot Number:	93537129	VG536347	VG540309
Trace Code:	995510CH	995510CQ	995510CR
Assy lot number	995510CH01	995510CQ01	995510CR01
Raw Line Code Package:	J55B*410ESXX	U05B*427ESXV	J15B*765ESXV
Reliability Lab location :	ST Muar (Malaysia)		

2.3 Front-End information

Front-End	Lot 1 (410)	Lot 2 (427)	Lot 3 (765)
Wafer Diameter:	8 inches		
Wafer Thickness:	375 +/-25 μ m		
Die Size:	3.3908 X 3.328 mm	3.263 X 4.199 mm	3.010 X 2.458 mm
Scribe Line size x/y:	80 x 80 μ m		
Pad Die Size /Pad type:	59 x 123 μ m	53 x 108 μ m	65 x 108 μ m
Metal Layers Number /Materials /Thickness:	Metal 1 Tin/AlCu/Tin 0.450 μ m Metal 2 Tin/AlCu/Tin 0.450 μ m Metal 3 Tin/AlCu/Tin 0.450 μ m Metal 4 Tin/AlCu/Tin 0.450 μ m Metal 5 Tin/AlCu/Tin 0.875 μ m	Metal 1 TaN/Ta/Cu 0.280 μ m Metal 2 Ti/AlCu/TxTN 0.310 μ m Metal 3 Ti/AlCu/TxTN 0.310 μ m Metal 4 Ti/AlCu/TxTN 0.310 μ m Metal 5 Ti/AlCu/TxTN 1.200 μ m	Metal 1 TaN/Ta/Cu 0.280 μ m Metal 2 TaN/Ta/Cu 0.350 μ m Metal 3 TaN/Ta/Cu 0.350 μ m Metal 4 Ti/AlCu/TxTN 0.900 μ m
Passivation Layers Thickness:	HDPox 10kA+SRO 1.5kA+PESIN 6kA	USG + NitUV (HFP USG+UV Nitride)	
Back Metal Finishing	RAW SILICON - BACK GRINDING		

2.4 Back-End information

Back-End	Lot 1 (410)	Lot 2 (427)	Lot 3 (765)
Assembly Plant Location/ Address:	ST MICROELECTRONICS TANJONG AGAS IND ESTATE PO BOX 28 84007 MUAR / JOHOR MALAYSIA		
Die Thickness after Back grinding:	NA	NA	NA
Die sawing method:	Step cut		
Die attach material:	Glue		
Type:	EN4900		
Supplier:	ST16		
Lead frame material:	Copper LF-HD LQFP 48L 7x7		Copper LF-HD LQFP 48L 7x7
L/F Finishing	Rough μ PPF (e4) Ni Pd AuAg		Rough μ PPF (e4) Ni Pd AuAg
Type:	5 x 5		3.6 x 3.6
Die paddle size:	HDS		HDS
Supplier:	Hitachi		
Wire bonding:	AG 96,5% WIRE		
Type	0.8MIL		
/Diameter:	MKE		
Supplier:			
Pitch:	80 μ m	70 μ m	80,36 μ m
POA:	0110596		
Molding Compound Supplier:	EME-G700LS SUMITOMO		
Package Moisture Sensitivity Level (JEDEC J-STD020D):	2		

3 RELIABILITY RESULTS SUMMARY

3.1 Die oriented test

Die Related Tests						Results LQFP 7x7		
Description	Test/Method	Conditions	Sample Size	Criteria	Readout / Duration	410	427	765
<i>Electrostatic discharge – Charge Device Model</i>								
ESD CDM	ANSI/ESD STM5.3.1	500V 1KV	3 units	500V for dice 410/427 1KV for 765	NA	0/3	0/3	0/3

3.2 Package Oriented Test

Package Related Tests						Results LQFP 7x7		
Description	Test/Method	Conditions	Sample Size	Criteria	Readout / Duration	410	427	765
<i>Preconditioning: moisture sensitivity level 1</i>								
PC	J-STD-020 JESD22-A113	MSL1 For MSL2 Qual	308 units	Electrical test: A0/R1 (Accepted 0 reject/ Rejected 1 reject)	NA	0/308		
<i>High Temperature Storage Life</i>								
HTSL	JESD 22-A103	150°C	77 units	Elect test A0/R1	1000h	0/77	0/77	0/77
<i>Thermal Cycling after Preconditioning</i>								
TC	JESD 22-A104	-65c/+150°c	77 units	Elect test A0/R1	100cy	0/77	0/77	0/77
					500cy	0/77	0/77	0/77
					1000cy	0/77	0/77	0/77
<i>Wire Bond Shear after Thermal Cycling</i>								
Wire Bond Shear	AEC Q100-001	Min bond shear 15g after TC	30 x 3	A0/R1	After TC 500cy TC 1000cy	0/30	0/30	0/30
<i>Wire Bond Pull after Thermal Cycling</i>								
Wire Bond Pull	Mil Std 883 Method 2011	Minimum pull strength after TC=3 grams after TC	30 x 3	A0/R1	After TC 500cy TC 1000cy	0/30	0/30	0/30

<i>Autoclave after Preconditioning</i>									
AC	JESD 22A102	121°C ,100% 2Atm RH	77 units	Elect test A0/R1	96h	0/77	0/77	0/77	
<i>Temperature Humidity Bias after Preconditioning</i>									
THB	JESD 22A110	85°C/85%RH Bias	77 units	Elect test A0/R1	1000h	0/77	0/77	0/77	
<i>Construction Analysis</i>									
CA	Construction Analysis including : -Wire bond shear -Wire bond pull -Solderability -Physical Dimension	JESD 22B102 JESDB100/B108	50		No major concern	No major concern			

4 APPLICABLE AND REFERENCE DOCUMENTS

ADCS/DMS 0061692 :	Reliability Tests And Criteria For Qualifications
SOP 2.6.2:	Process qualification and transfer management
SOP 2.6.7:	Product Maturity Level
SOP 2.6.9:	Package and process maturity management in Back End
SOP 2.6.11:	Program management from product qualification
SOP 2.6.19:	Process maturity level
ANSI-ESD STM5.3.1:	Electrostatic discharge (ESD) sensitivity testing charge device model (CDM)
JESD 22-A103	High Temperature Storage Life
J-STD-020D:	Moisture/reflow sensitivity classification for non-hermetic solid state surface mount devices
JESD22-A113:	Preconditioning of non-hermetic surface mount devices prior to reliability testing
JESD22-A102:	Autoclave test (pressure pot)
JESD22-A104:	Temperature cycling
JESD22-A110:	Temperature Humidity Bake
JESD 22B102:	Solderability test
JESD22B100/B108:	Physical dimension

5 GLOSSARY AND TESTS DESCRIPTION

PC	Preconditioning (solder simulation)
THB	Temperature Humidity Bias
TC	Temperature cycling
AC	Autoclave test (pressure pot)
HTSL	High temperature storage life
ADCS/DMS	ST Advanced Documentation Controlled system/ Documentation Management system
ESD CDM	Electrostatic discharge (charge device model)
CA	Construction Analysis

6 REVISION HISTORY

Version	Date	Author	Comment
1.0	May 31st, 2016	Olivier GIRAUD	Initial release for qualification

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**PRODUCT/PROCESS
CHANGE NOTIFICATION
PCN13410
– Additional information**

**ST MUAR (Malaysia) die attach material (Glue) additional source
for STM32 LQFP 14x14 SHD 100L package - on listed products**

MDG - Microcontrollers Division (MCD)

What are the changes?

Changes described in table below:

	Existing back-end lines	Added back-end line
Assembly site	ST Muar Malaysia	
Die Attach Material	GLUE LOCTITE ABLESTIK ABP8302	GLUE HITACHI EN4900GC



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How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number "**PCN13410**" into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

%: 0 Sample Type: Sample Non Std Type

Closing Type: Sample Std Type
Sample Non Std Type
Sample Non Std w Spl Tests

Lab Sheet:

SO | NPO Sample

Header
SO Nr: 0018502433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J
PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:
Notes: Status: 01 All items pending,ni Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust:
PO Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 8800367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Notes: TAM K Pieces: 0 Our Share%: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet: PCN 10595

Lab Sheet:



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PCN Title : ST MUAR (Malaysia) die attach material (Glue) additional source for STM32 LQFP 14x14 SHD 100L package - on listed products

PCN Reference : MDG/22/13410

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F103VCT6TR	STM32F103VDT6	STM32F101VCT6
STM32F101V8T6	STM32F071V8T6	STM32F071V8T7
STM32F103VDT7	STM32F103VBT6TR	STM32F103VDT6TR
STM32F103VBT6	STM32F100VBT6BTR	STM32F071V8T6TR
STM32F107VBT6	STM32F100V8T6BTR	STM32F071V8T7TR
STM32F101V8T6TR	STM32F105V8T6	STM32F103V8T6TR
STM32F101VBT6	STM32F103VBT7	STM32F103VGT6TR
STM32F078VBT6	STM32F302VBT6TR	STM32F103VBT7TR
STM32F103VET6TR	STM32F100VCT6B	STM32F103VGT7TR
STM32F071VBT6	STM32F101VCT6TR	STM32F101VDT6TR
STM32F105VBT6	STM32F303VCT6	STM32F072VBT6
STM32F103VFT7	STM32F105VCT6TR	STM32F101VBT6TR
STM32F091VCT6	STM32F091VCT7	STM32F103VET6
STM32F103VET7TR	STM32F101VET6	STM32F303VBT6TR
STM32F398VET6	STM32F091VCT7TR	STM32F302VBT6
STM32F107VCT6TR	STM32F071VBT6TR	STM32F103VFT6
STM32F107VCT7	STM32F103V8T6	STM32F302VCT6TR
STM32F303VCT6TR	STM32F302VCT7	STM32F072VBT6TR
STM32F303VBT7	STM32F100VET6BTR	STM32F103VFT6TR
STM32F105VCT6	STM32F101VET6TR	STM32F105V8T6TR
STM32F091VCT6TR	STM32F302VET6TR	STM32F302VDT6TR
STM32F100VDT7B	STM32F091VBT6	STM32F303VBT6
STM32F103VGT6	STM32F100VBT7B	STM32F302VCT7TR
STM32F303VDT6	STM32F100VCT6BTR	STM32F100VET7B
STM32F101VFT6	STM32F100VBT6B	STM32F103VGT7
STM32F100V8T7B	STM32F101VFT6TR	STM32F303VET6
STM32F101VDT6	STM32F101VGT6	STM32F103VCT6
STM32F098VCT6	STM32F105VCT7	STM32F100VET6B
STM32F072V8T6	STM32F303VCT7	STM32F303VET7
STM32F091VBT7	STM32F107VCT6	STM32F103VET7
STM32F302VDT6	STM32F100VDT6BTR	STM32F100VDT6B
STM32F358VCT6	STM32F100V8T6B	STM32F302VET6
STM32F302VCT6	STM32F303VDT6TR	STM32F303VCT7TR
STM32F103VDT7TR	STM32F303VET6TR	



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